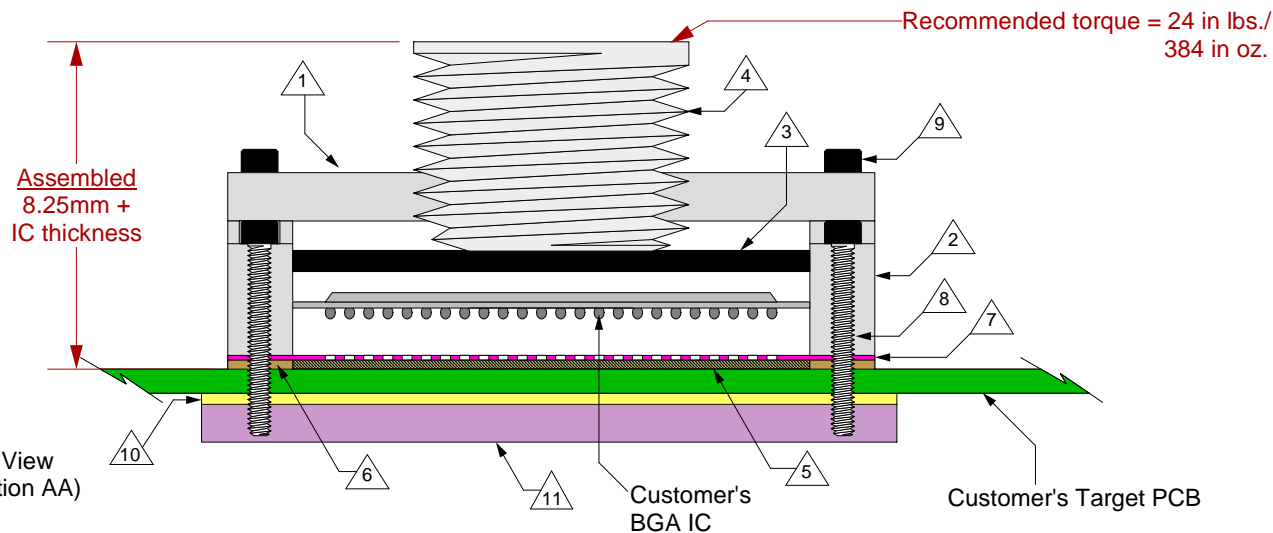
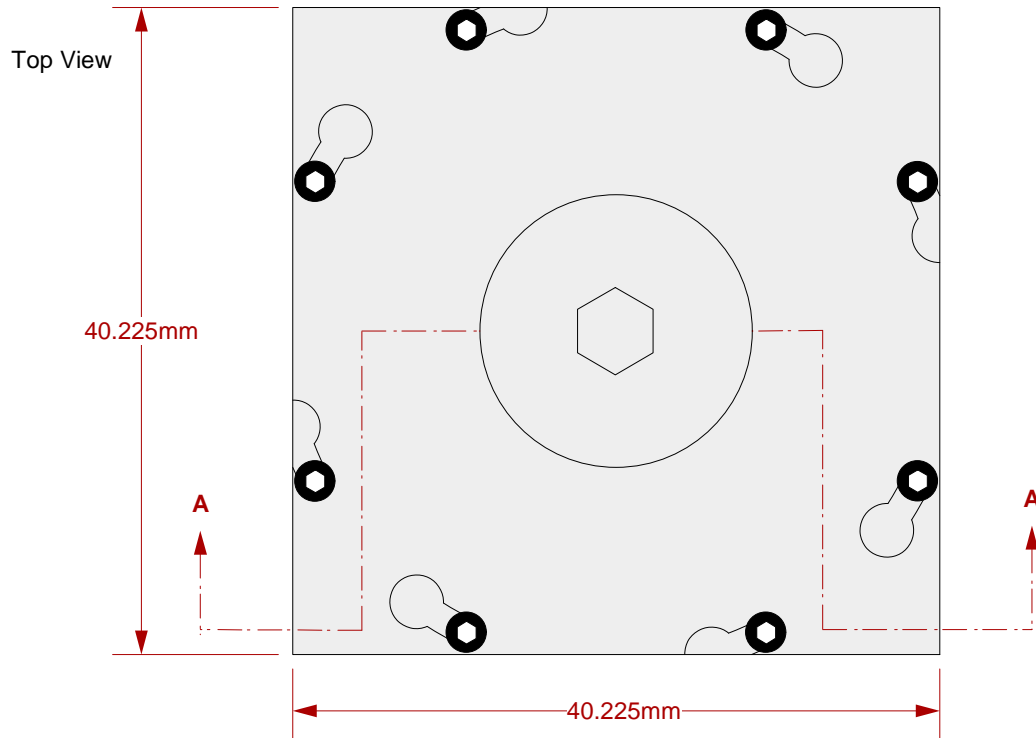


# GHz BGA Socket - Direct mount, solderless

## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Cirlex or equivalent. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

## SG-BGA-6020 Drawing

Status: Released

Scale: -

Rev: G



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Tele: (952) 229-8200  
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Drawing: H. Hansen

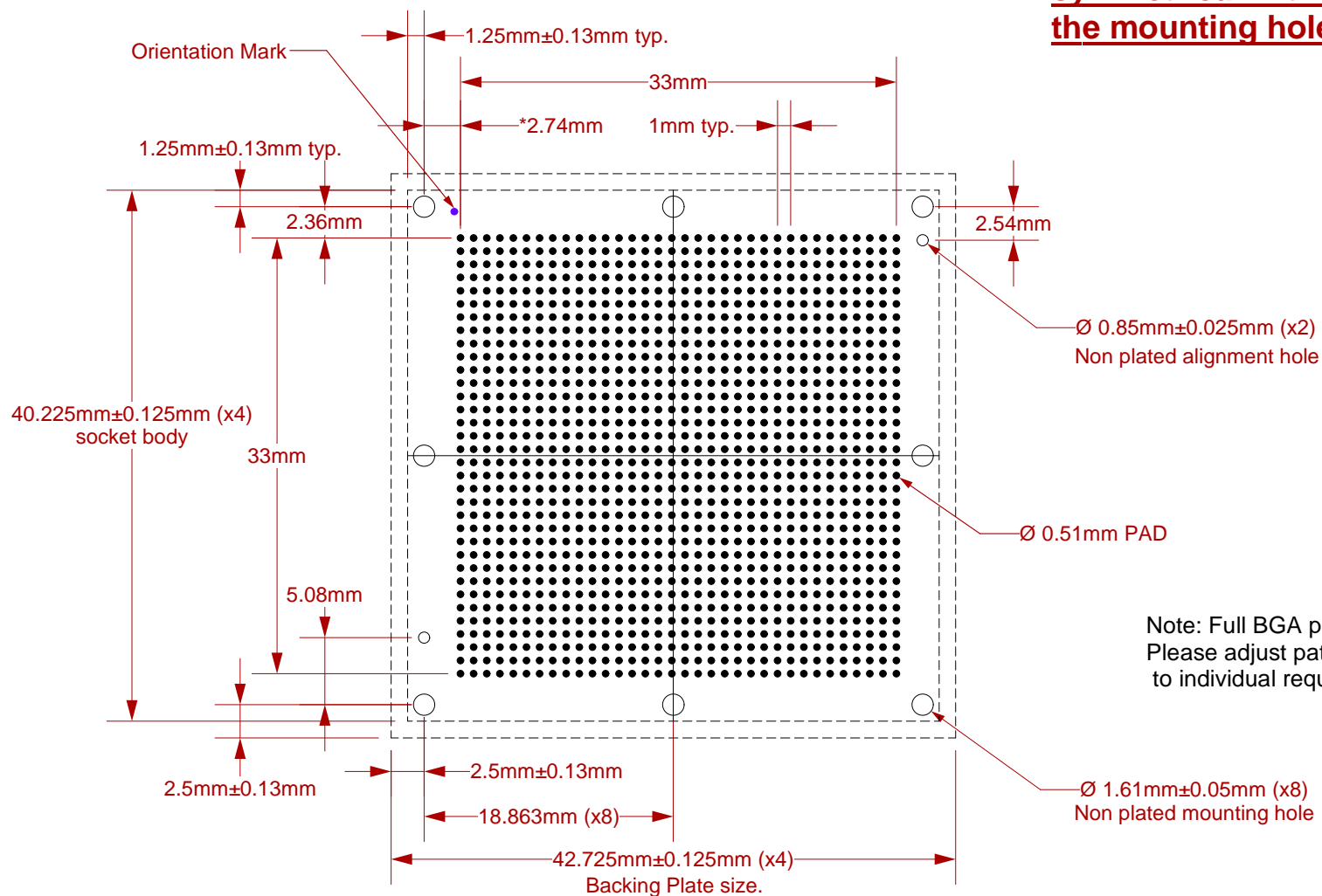
Date: 11/26/01

File: SG-BGA-6020 Dwg

Modified: 6/15/09, AE

All tolerances:  $\pm 0.125$ mm (unless stated otherwise). Materials and specifications are subject to change without notice.

**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Note: Full BGA pattern shown. Please adjust pattern according to individual requirements.

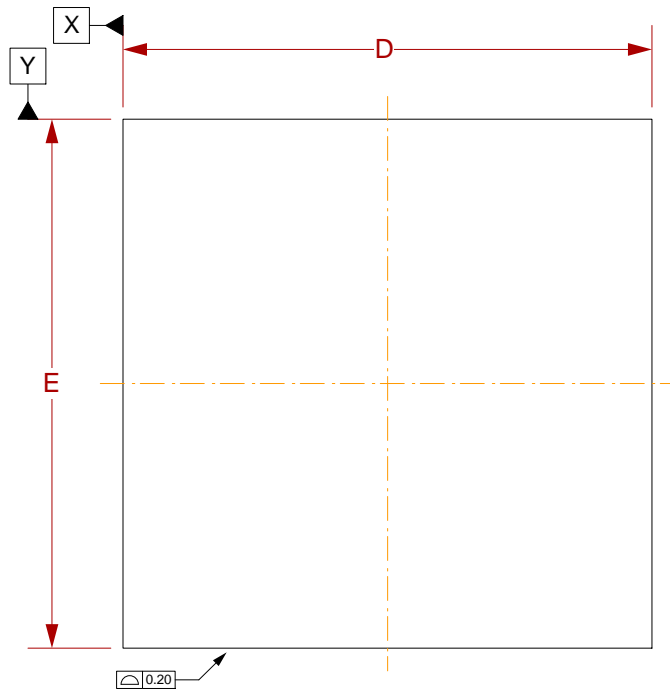
Target PCB Recommendations

Total thickness: 2.4mm min.  
Plating: Gold or Solder finish  
PCB Pad height: Same or higher than solder mask

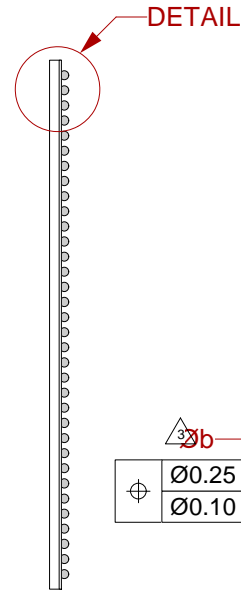
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

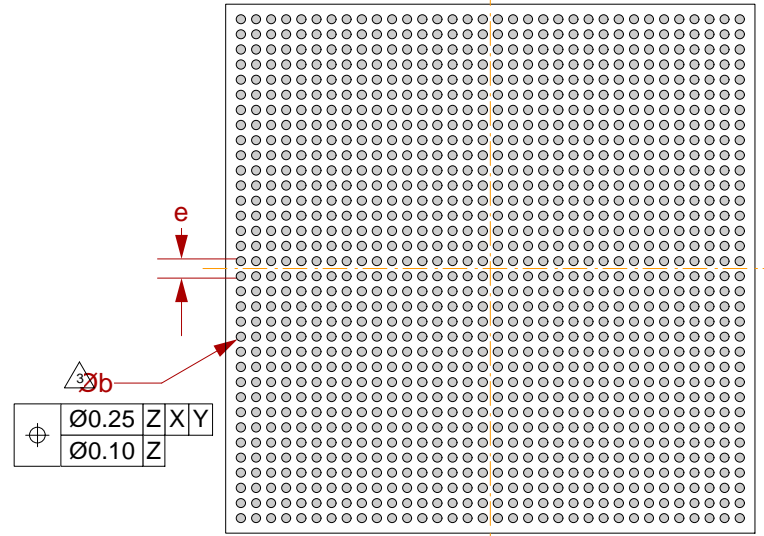
<b>SG-BGA-6020 Drawing</b>		Status: Released	Scale: -	Rev: G
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: H. Hansen		Date: 11/26/01	
	File: SG-BGA-6020 Dwg		Modified: 6/15/09, AE	



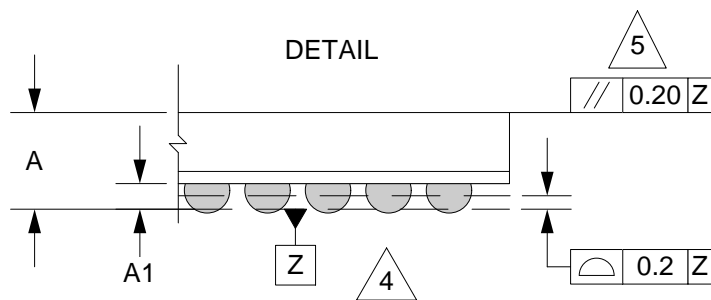
TOP VIEW



SIDE VIEW




BOTTOM VIEW



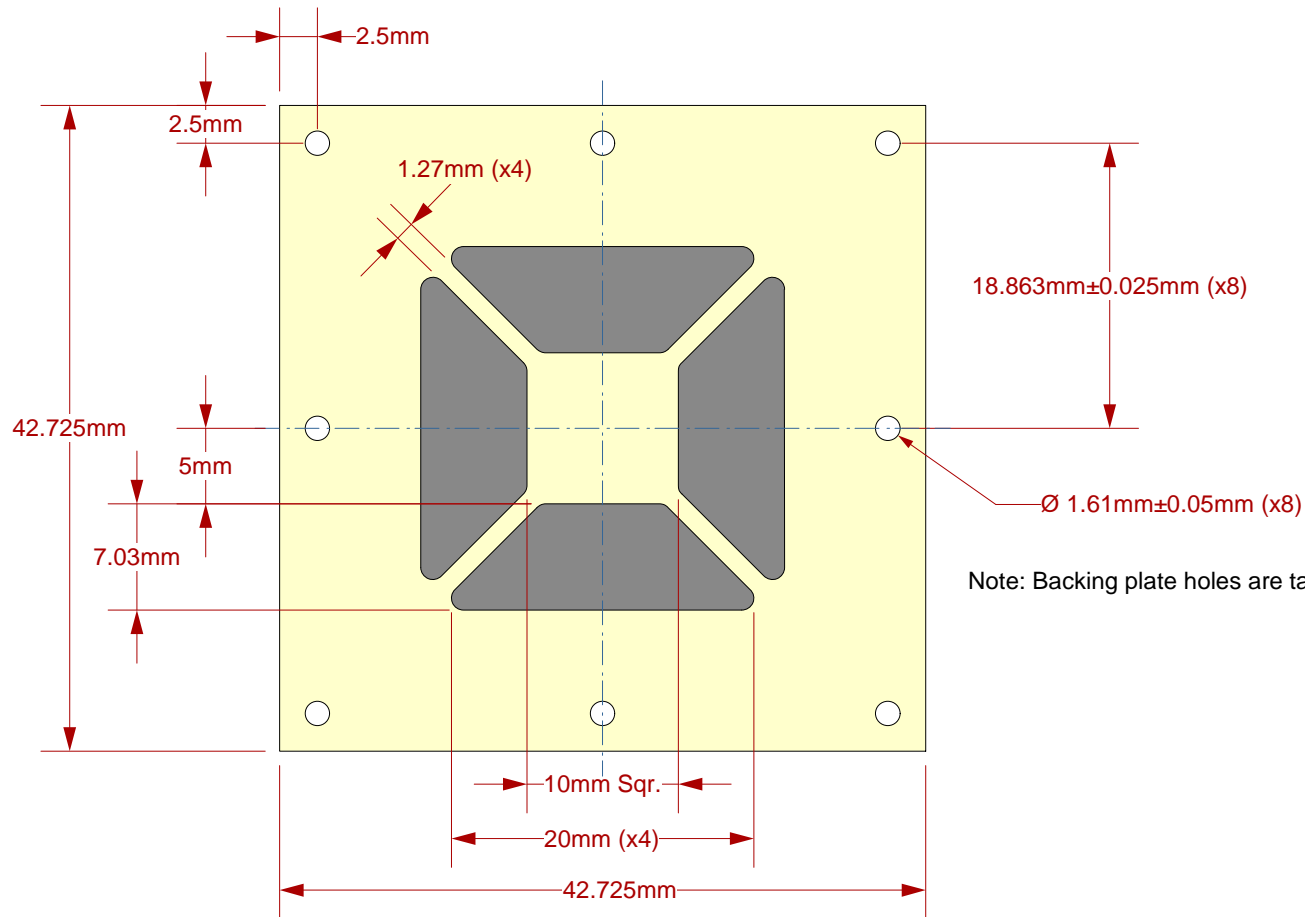
- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.6
A1	0.4	0.6
b	0.5	0.7
D	35.0 BSC	
E	35.0 BSC	
e	1.00 BSC	

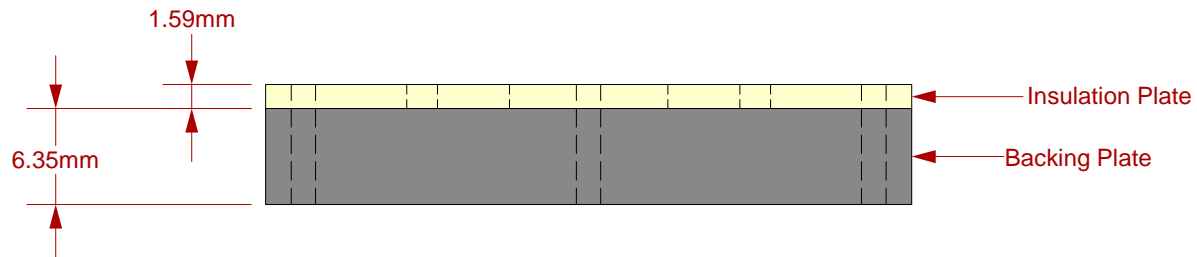
Array 34x34

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	Drawing: H. Hansen		Date: 11/26/01	
	File: SG-BGA-6020 Dwg		Modified: 6/15/09, AE	

Top View




Side View



Description: Insulation Plate and Backing Plate

All dimensions are in mm.  
All tolerances are +/- 0.125mm.  
(Unless stated otherwise)

	<b>SG-BGA-6020 Drawing</b>	Status: Released	Scale: -	Rev: G
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